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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

13
92

APPL NUM 10034030	FILING DATE 12/19/2001	CLASS 438	SUBCLASS 859	GAU 3729 2812	EXAMINER Trinh D. Nguyen
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**APPLICANTS: Horng Gwo-Ji; Kuo Jen-I; Hsiau Feng-Ger;

**CONTINUING DATA VERIFIED: *No*

** FOREIGN APPLICATIONS VERIFIED: *No*

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO JCLA8482
TITLE : Method of fabricating a ceramic substrate with a thermal conductive plug of a multi-chip package			

U.S. DEPT. OF COMM /PAT. & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner Total Claims Print Claim for O.G.	
		DRAWING Sheets Drwg. Figs. Drwg. Print Fig.	
ISSUE FEE Amount Due Date Paid		Minh Trinh Primary Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE Application Examiner	
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